



# Nanoelectronics Trends for the Next Decade

nano2

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Dr. Jeffrey Welser

Director, SRC Nanoelectronics Initiative

## Presentation Sources:

Nanotechnology Research Directions for Societal Needs in 2020: Retrospective and Outlook

*Chapter 8. Applications: Nanoelectronics and Nanomagnetism* (J. Welser, S. Wolf, P. Avouris, T. Theis)

- Full Report to be published (Springer, Boston and Berlin, 2010)
- PDF Version available online: <http://www.wtec.org/nano2/>

Semiconductor Research Corporation (SRC) Nanoelectronics Research Initiative

<http://nri.src.org>

## Additional References:

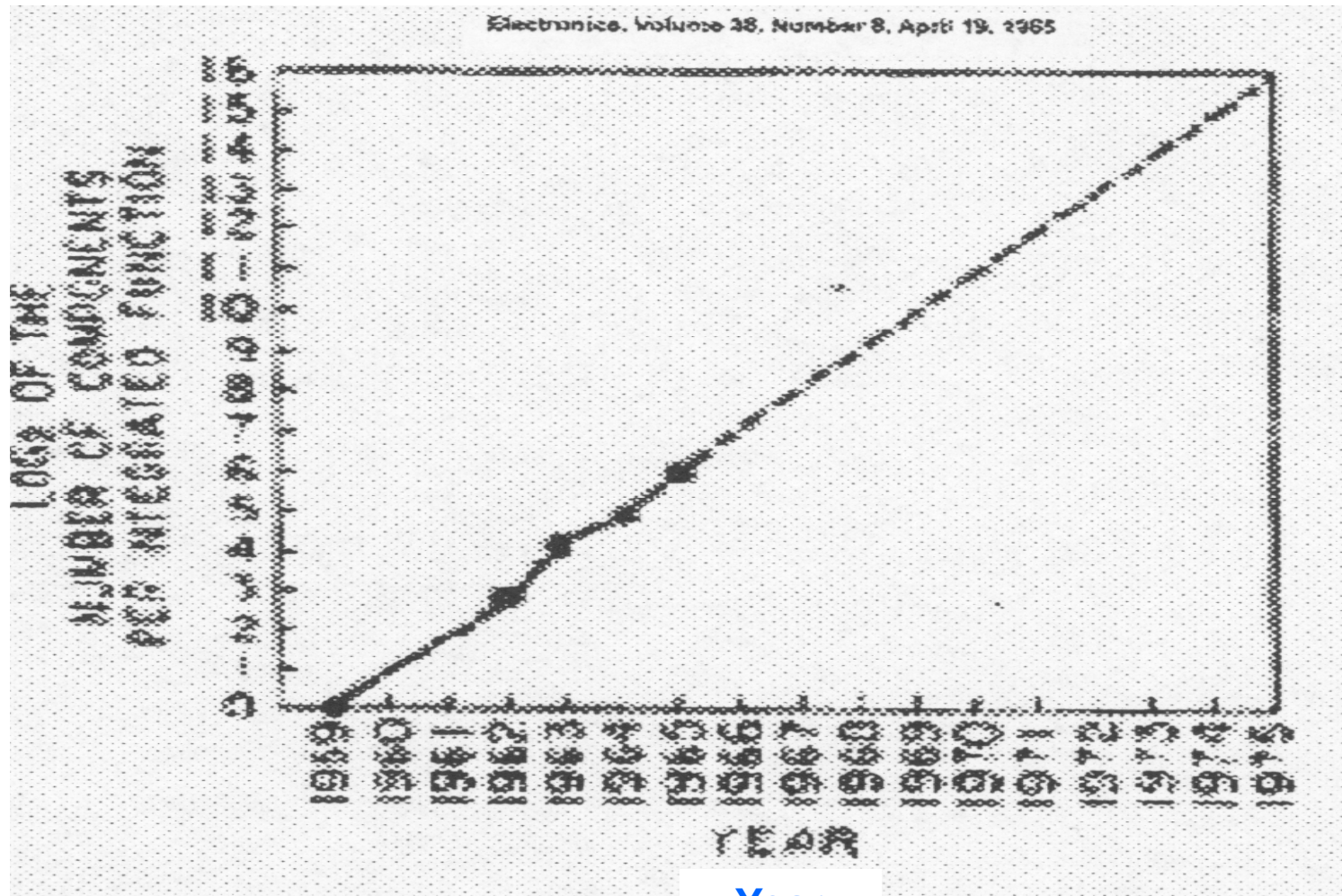
International Technology Roadmap for Semiconductors (ITRS)

*Emerging Research Devices (ERD) and Emerging Research Materials (ERM) Chapters*

<http://www.itrs.net/Links/2010ITRS/Home2010.htm>

Electronics, Volume 38, Number 8, April 19, 1965

Log of the Number of Components  
Per Integrated Function



Year

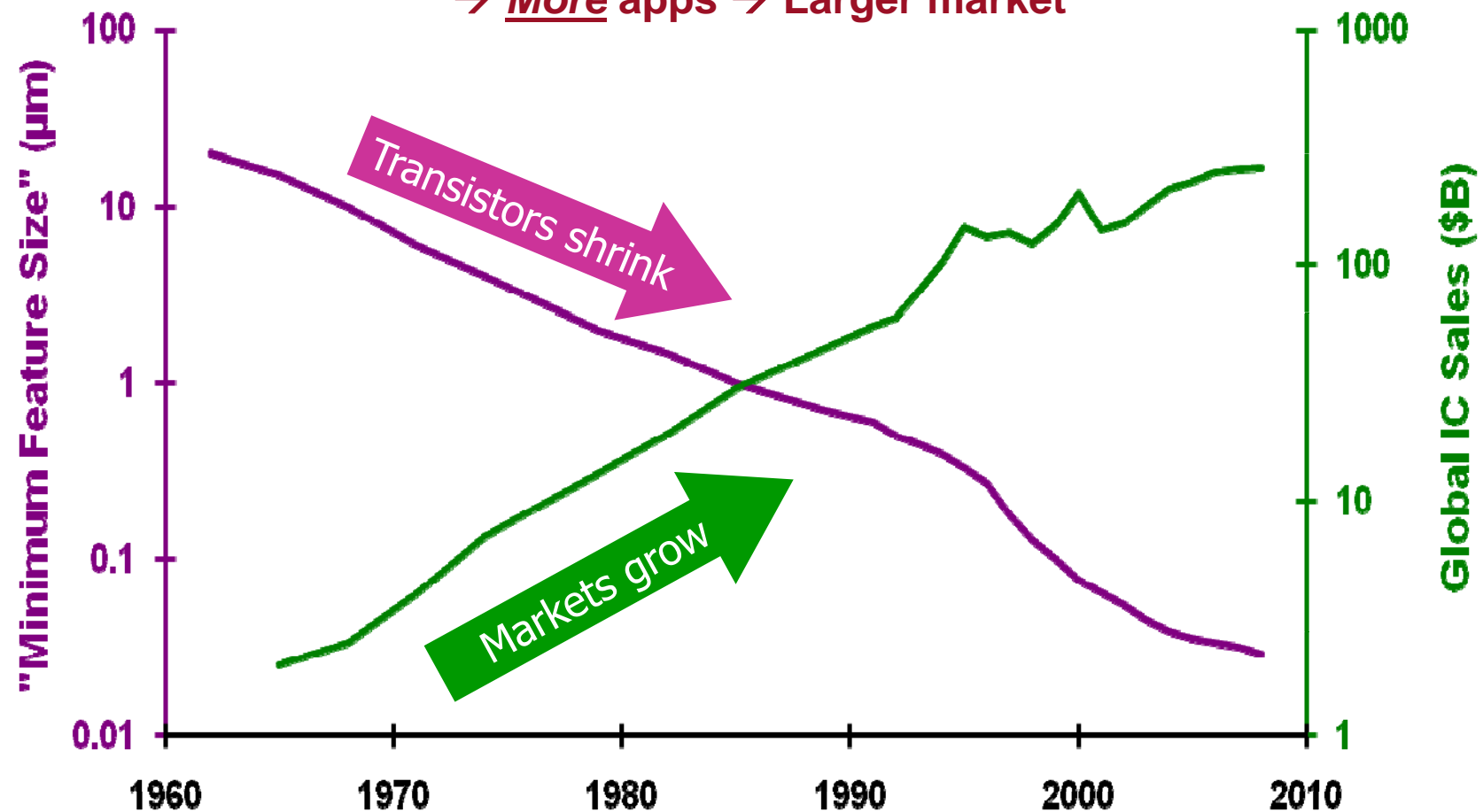


# Nanoelectronics Most Visible Impact

## *Scaling Drives the Semiconductor Industry*



Smaller features → Better performance & cost/function  
→ More apps → Larger market

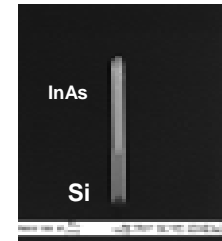
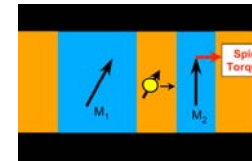
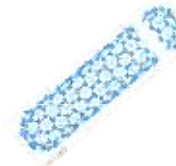


Courtesy of R. Doering, Texas Instruments;  
Data from Semiconductor Industry Association, <http://www.sia-online.org>

# Advances in Last Ten Years: From Science to Product

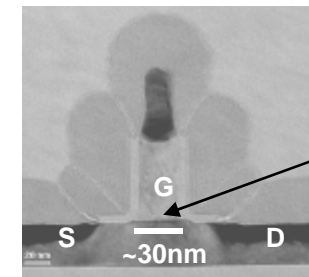
## ➤ Science/Engineering Level:

- Expansion of Carbon Electronics: (Re-)discovery of graphene; advances in nanotube fabrication and selection
- Emergence of Spintronics:
  - Demonstration of Spin Torque switching
  - Discovery of magnetoelectric / multiferroic materials
  - Discovery of the Spin Hall Effect
  - Demonstrations of spin injection and readout from semiconductors
- Advances in resistive memory: Phase-Change, metal oxides
- Fundamental understanding of semiconductor nanowire growth



## ➤ Product Level:

- CMOS and FLASH scaled down to ~30nm
- Magnetic Tunnel Junctions (MTJs)
  - Read Heads for Magnetic Recording; Magnetic RAM
- Phase Change High Density Memory



Insulator:  
SiON ~ 1nm or  
High-k ~3nm

## ➤ Impact: Exponential increase in the capability and mobility of electronic devices:

A cellphone is now a computer, internet access device, stereo, video camera, game machine, GPS, etc.





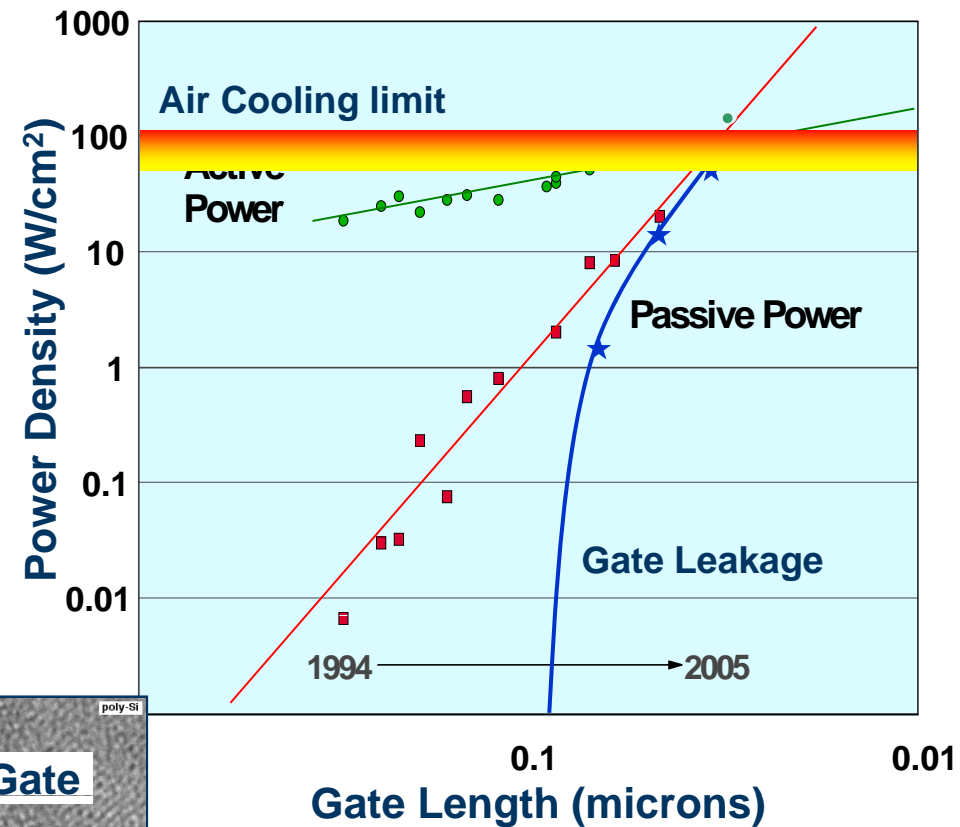
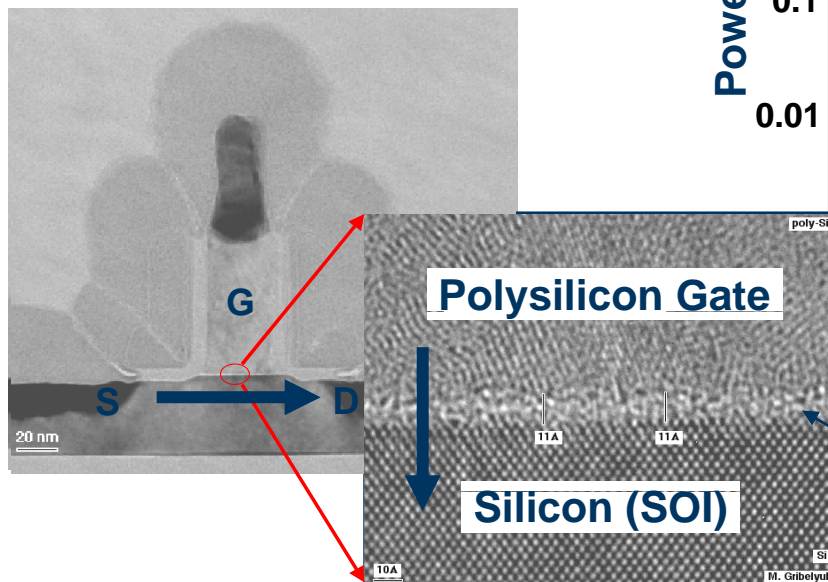
# Future Scaling: Power is THE Issue

*Must find a lower energy device*

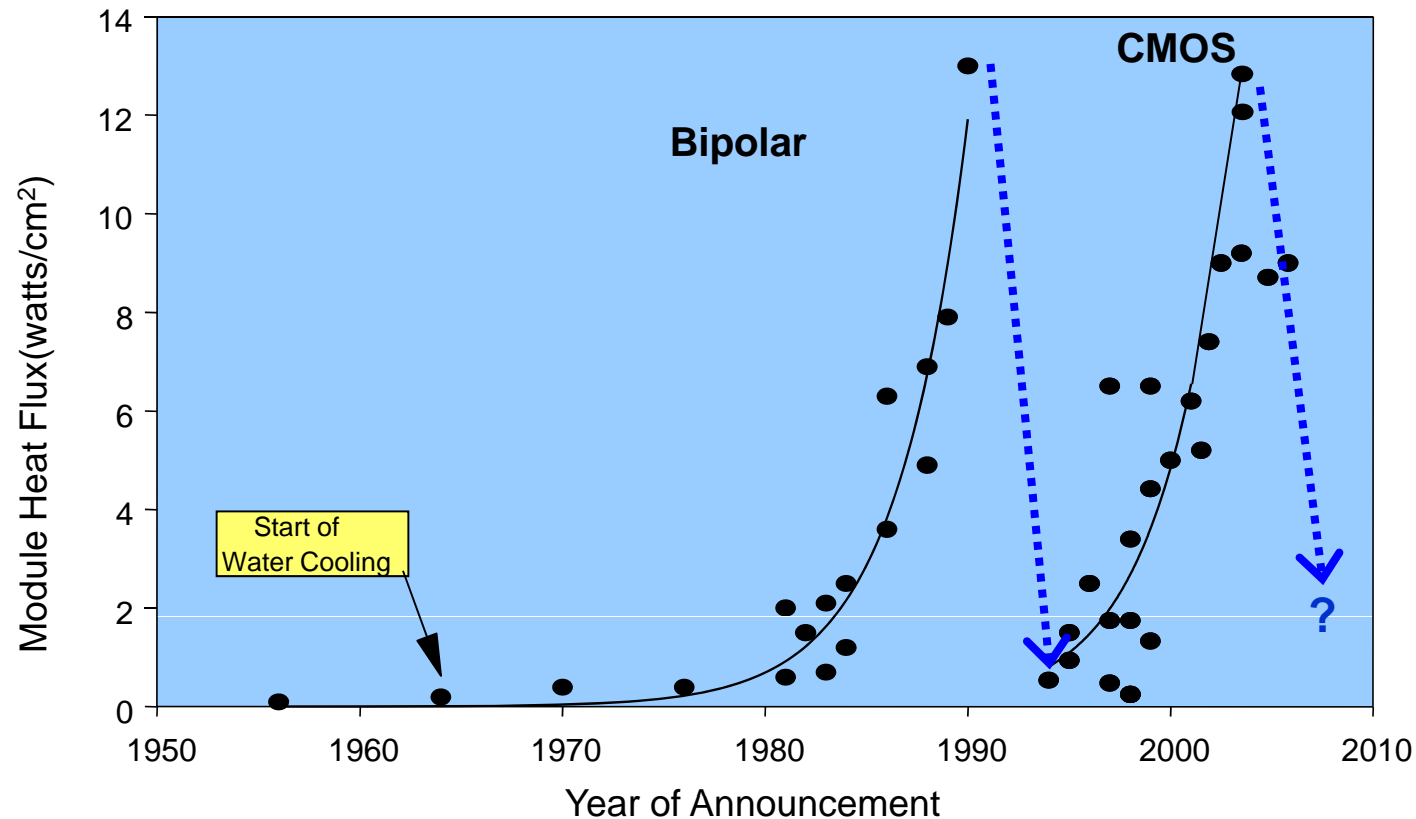


## Power components:

- Active power
- Passive power
  - Gate leakage
  - Source - Drain leakage







- 2005 ~ 2015: New technology enhancements → Mainstream university and industry Research
  - Continued CMOS shrinking, low-power FET devices, multi-core chips, 3D packaging, new memory devices, etc.
- > 2015? : New device technology → NRI Research



# Nanoelectronics Research Initiative

## *Mission Statement*

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**NRI Mission: Demonstrate novel computing devices capable of replacing the CMOS FET as a logic switch in the 2020 timeframe.**

- These devices should **show significant advantage over ultimate FETs** in power, performance, density, and/or cost to enable the semiconductor industry to **extend the historical cost and performance trends** for information technology.
- To meet these goals, NRI pursues **five research vectors**, focused on discovering and demonstrating new devices and circuit elements for doing computation.
- Finally, it is desirable that these technologies be **capable of integrating with CMOS**, to allow exploitation of their potentially complementary functionality in heterogeneous systems and to enable a smooth transition to a new scaling path.

- To beat the power problem requires:
  - A device with a lower energy, room temperature switching mechanism  
or
  - A system that operates out of equilibrium or recovers operation energy as part of the logic computation

- **Required characteristics:**

- Scalability
- Performance
- Energy efficiency
- Gain
- Operational reliability
- Room temp. operation

- **Preferred approach:**

- CMOS process compatibility
- CMOS architectural compatibility



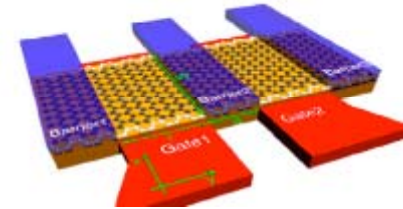
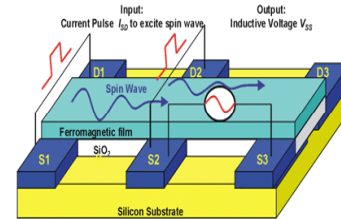
- **Alternative state variables**

- Spin–electron, nuclear, photon
- Phase
- Quantum state
- Magnetic flux quanta
- Mechanical deformation
- Dipole orientation
- Molecular state



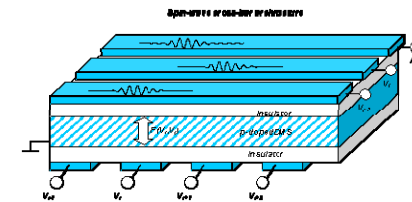
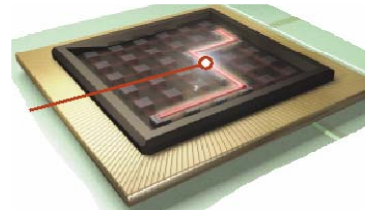
- **NEW DEVICE**

Device with alternative state vector



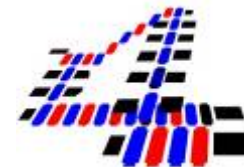
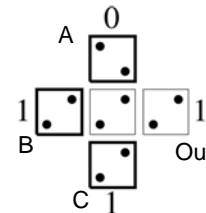
- **NEW WAYS TO CONNECT DEVICES**

Non-charge data transfer



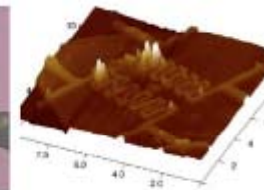
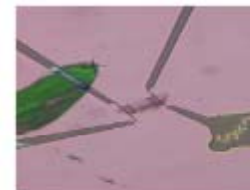
- **NEW METHODS FOR COMPUTATION**

Non-equilibrium systems



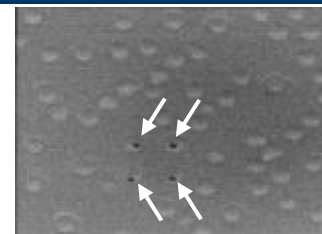
- **NEW METHODS TO MANAGE HEAT**

Nanoscale phonon engineering



- **NEW METHODS OF FABRICATION**

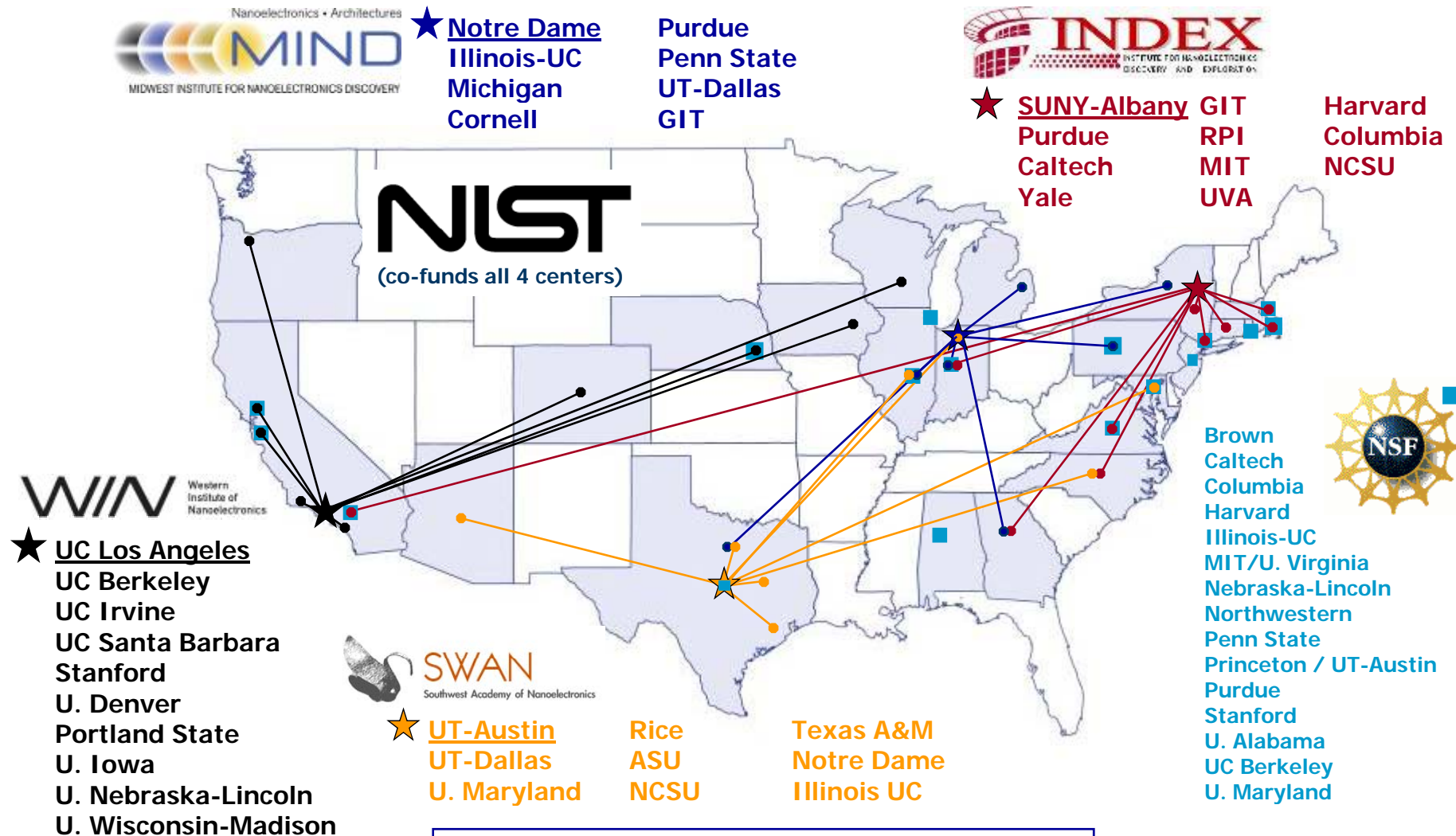
Directed self-assembly devices





# NRI Funded Universities

## *Finding the Next Switch*



Over 35 Universities in 22 States



# NRI Research Centers

## *In Partnership with NIST*

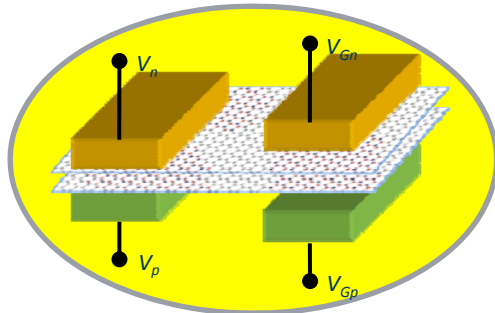


- Leveraging industry, university, and both state & fed government funds, and driving university nanoelectronics infrastructure

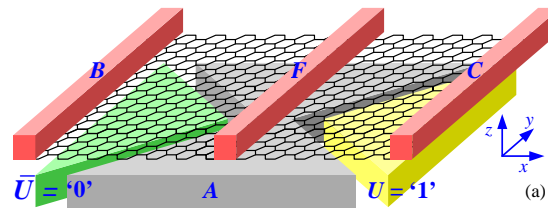


<b>WIN</b> Western Institute of Nanoelectronics	<b>INDEX</b> Institute for Nanoelectronics Discovery & Exploration	<b>SWAN</b> SouthWest Academy for Nanoelectronics	<b>MIND</b> Midwest Institute for Nanoelectronics Discovery
<b>UCLA</b> , UCSB, UCB, UC-Irvine, Stanford, U Denver, Iowa, Portland State, U Nebraska, U Wisconsin	<b>SUNY-Albany</b> , GIT, RPI, Harvard, MIT, Purdue, Yale, Columbia, Caltech, NCSU, UVA	<b>UT-Austin</b> , UT-Dallas, TX A&M, Rice, ASU, Notre Dame, Maryland, NCSU, Illinois-UC	<b>Notre Dame</b> , Purdue, Illinois-UC, Penn State, Michigan, UT-Dallas, Cornell, GIT
Spin devices Spin circuits Benchmarks & metrics Spin Metrology	Novel state-variable devices Fabrication & Self-assembly Modeling & Architecture Theory & Simulation Roadmap Metrology	Logic devices with new state-variables Materials & structures Nanoscale thermal management Interconnect & Arch Nanoscale characterization	Graphene devices: Thermal, Tunnel, & Spin Interband Tunnel Devices NanoMagnetic Logic Non equilibrium Systems Model / Measurement Nanoarchitecture

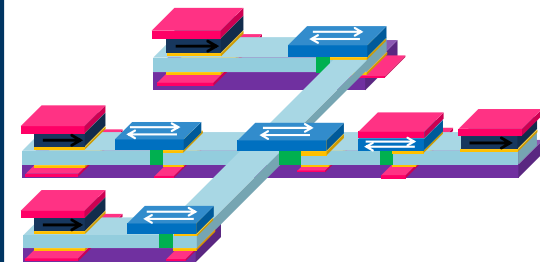
**Graphene Bilayer  
pseudoSpin FET**  
UT Austin



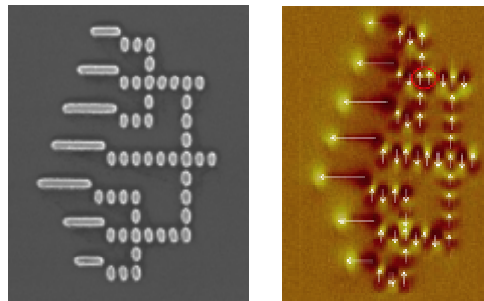
**Graphene PN Junction**  
SUNY Albany



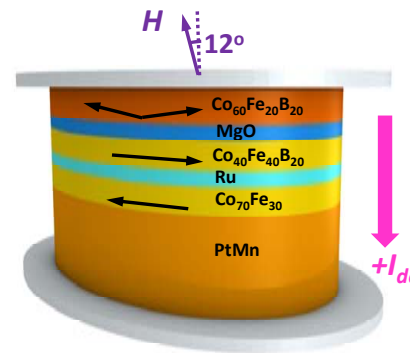
**All-Spin Logic**  
Purdue U.



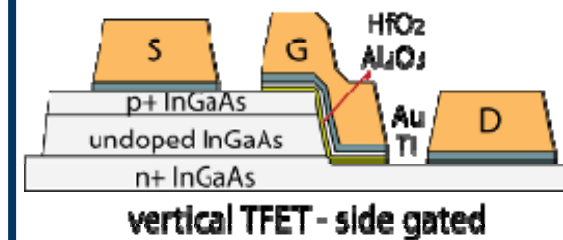
**Nanomagnet Logic**  
Notre Dame, Berkeley



**Spin-Torque Device**  
UCLA



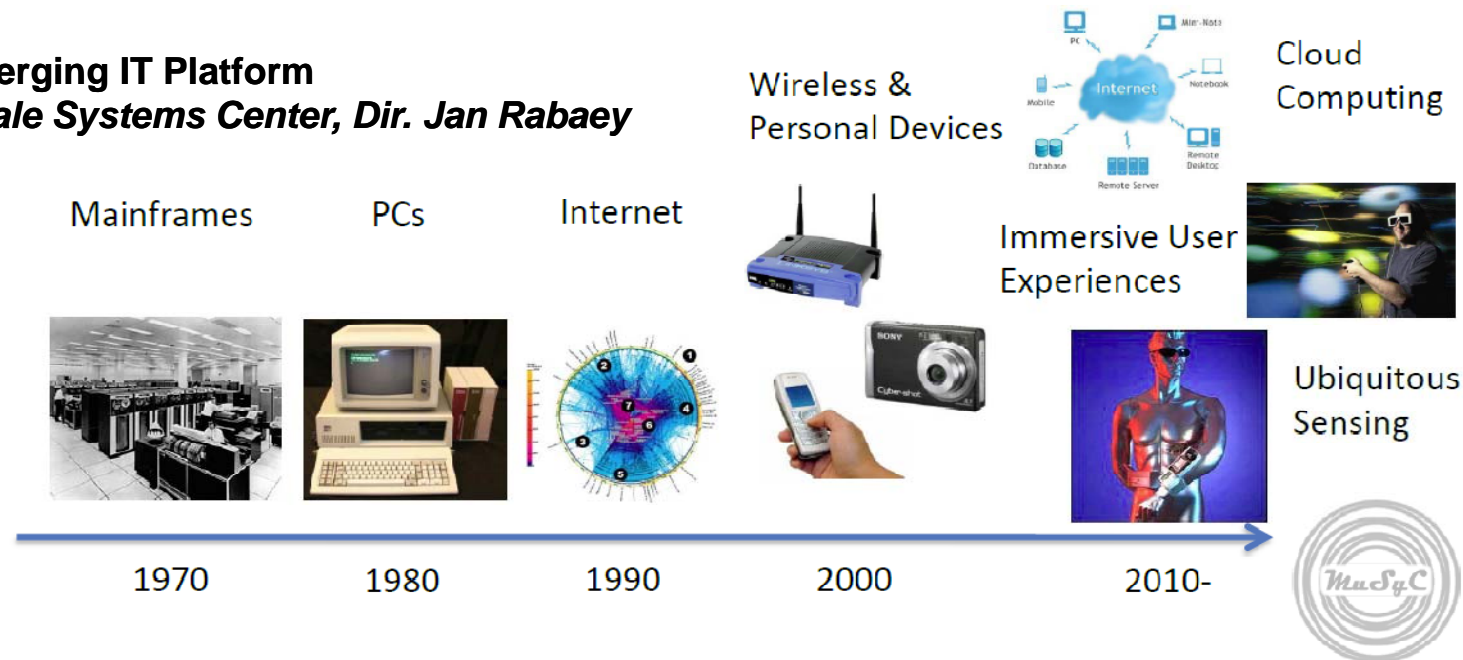
**Heterojunction TFET**  
Penn. State, Notre Dame



# Vision Changes in Last Ten Years: From How to Build → What to Build

- Barrier to future scaling changing from just “how do we make them smaller?” to “how do we reduce their power to make them usable?”
  - Shift from breaking below 100nm Si CMOS to breaking below 10nm
- Discovery of myriad new materials with new physics and properties driving new ideas for device functionality
- Shift from single device focus to circuits and architecture integration
- Increased emphasis on other application areas, beyond logic and memory for Information Technology (IT) infrastructure

## The Emerging IT Platform *Multiscale Systems Center, Dir. Jan Rabaey*







# Vision for the Next Ten Years:

## *Major Directions*

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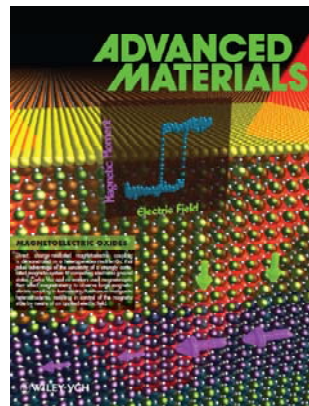
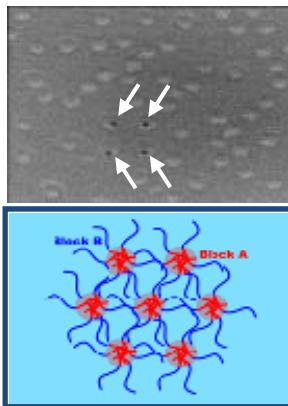


- Increased focus on utilizing new nanoscale physics for device functionality, rather than just fighting it to continue current device scaling
  - Alternate state variables for logic & memory
- Increased focus on architecture and alternative ways to do computation
  - Dealing with lower speeds for lower power: Multi-bit logic? Increased parallelism?
  - Dealing with increased variability: Analog / Statistical / “Almost Right” computation?
  - Tighter integration – and blurring – between memory and logic: Non-volatile transistors, memristors, memory-in-logic, reconfigurable logic, FPGAs
- Increased focus on spin, magnetics, Magnetic Tunnel Junctions – especially spin torque based structures
  - STT-RAM, Nano-oscillators, Magnetic Sensors, Spin Torque MTJ Logic, magnetic cellular automata, reconfigurable arrays
- Increased focus on Carbon based devices
  - Exploiting physics of graphene, carbon nanotubes, fullerenes, defects in diamond
- Increased focus on non-IT applications – future driver of the industry
  - Energy, healthcare, sensors everywhere, always-on connectivity, mobile devices

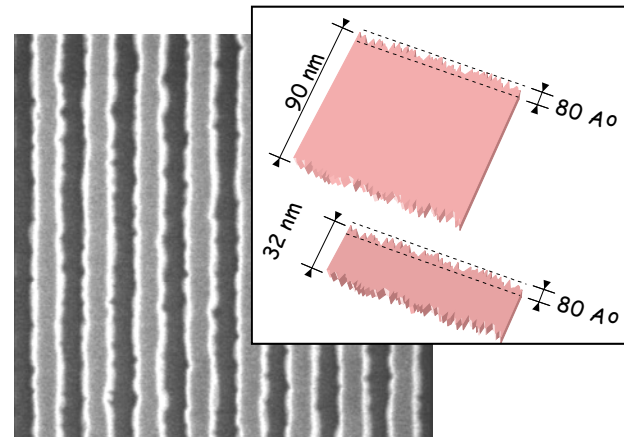


# Goals for 2020: *Fabrication*

- Achieve 3D near-atomic-level control of reduced-dimensional materials
  - Includes mono-layer growth, nano wire/tube/dot growth and placement, custom materials (e.g. complex metal oxides, multiferroics), and meta-materials (e.g. ferroelectric lattice with embedded ferromagnetic particles)



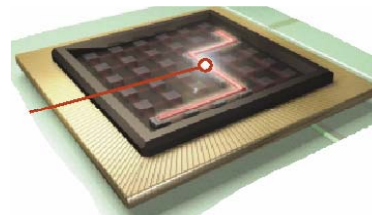
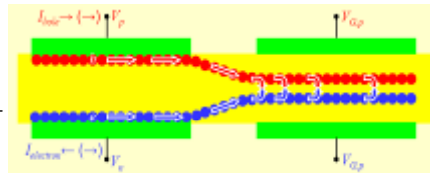
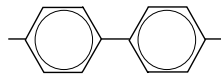
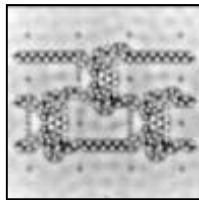
- Combine lithography and self-assembly to pattern semi-arbitrary structures down to 1nm precision
  - Requires both top-down control of litho for ~10nm-scale arbitrary structures, and bottoms-up control of self-assembly of 1nm-scale regular structures, plus improved inter-layer registration



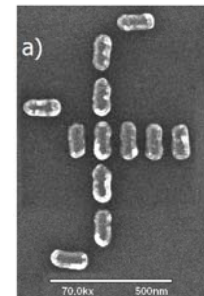
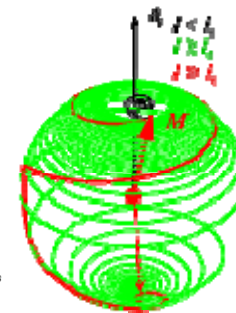
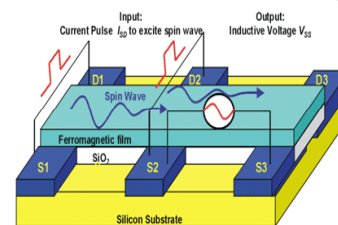
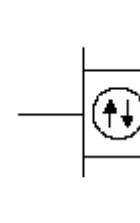
- Requires continued advances in:
  - Tools for growth, etching and placement at near-atomic levels
  - Chemistries for self-assembly
  - Metrology tools, including in-situ, dynamic characterization & in-line, non-invasive monitoring
  - Predictive modeling of materials and interfaces from atomic level up

# Goals for 2020: Devices


- Discover devices for logic and memory that operate with greatly reduced energy dissipation:  $10,000kT \rightarrow \sim 10kT$ 
  - Power density is the primary limiter of future scaling. Requires:
    - A device with a lower energy, room temperature switching mechanism
    - and/or
    - A system that operates out of equilibrium or recovers operation energy as part of the logic computation

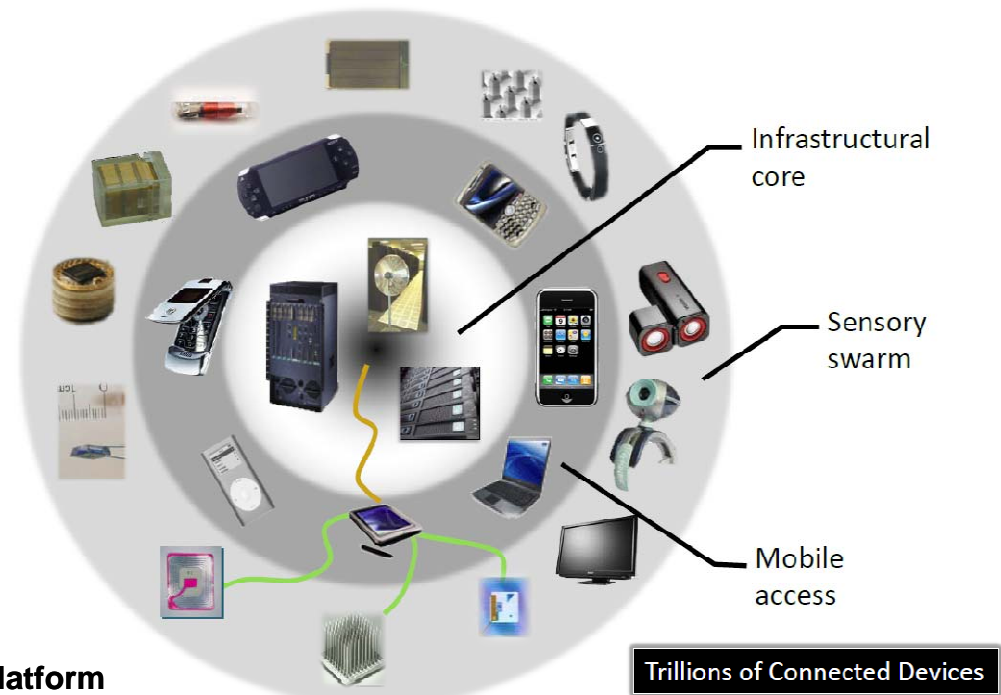


- Exploit spin for memory, logic, and new functionality
  - Spin and nano-magnetics offer unique attributes (non-volatility, precession, low power, spin-spin interaction) already utilized in memory and storage
  - New materials and nano-scale control should enable logic, solid state quantum computing, oscillators, sensors, and other functionality



- Challenges:
  - Finding appropriate architectures and state variables (spin, charge, collective effects, etc.)
  - Maintaining speed, noise robustness, signal strength, gain/drive

- Integrate architecture and nanoscale device research for unique computation functionality
  - Increase focus on emerging, non-IT applications
    - Previous research has focused on the device first, but most challenges are in the large-scale integration of any new device
    - Energy, healthcare, security, communications, sensors, flexible electronics all drive different needs at device and architecture level
    - Drives need for interdisciplinary teams – materials, chem/bio/physics, engineering, circuit design – working together on basic research driven by the application
- 
- The diagram illustrates a circular ecosystem of devices and technologies. At the center is a glowing sphere. Surrounding it are various electronic components and devices, including a smartphone, a laptop, a tablet, a smartwatch, a fitness tracker, a game console, a camera, a sensor module, a microchip, a battery, a flexible display, a small robot, a camera lens, a microphone, a speaker, a light sensor, a temperature sensor, a pressure sensor, a humidity sensor, a gas sensor, a pH sensor, a glucose sensor, a heart rate monitor, a blood pressure monitor, a glucose monitor, a smart home hub, a smart light bulb, a smart plug, a smart thermostat, a smart lock, a smart doorbell, a smart camera, a smart speaker, a smart display, a smart mirror, a smart window, a smart curtain, a smart lamp, a smart fan, a smart heater, a smart air purifier, a smart water filter, a smart water heater, a smart refrigerator, a smart oven, a smart microwave, a smart dishwasher, a smart washing machine, a smart dryer, a smart vacuum cleaner, a smart robot, a smart car, a smart truck, a smart plane, a smart ship, a smart satellite, a smart drone, a smart rocket, a smart space station, a smart planet, a smart galaxy, and a smart universe. Labels on the right side of the diagram point to different layers: 'Infrastructure core' points to the innermost layer, 'Sensors and actuators' points to the middle layer, and 'Mobile access' points to the outermost layer.



**The Emerging IT Platform**  
***Multiscale Systems Center, Dir. Jan Rabaey***



# International Perspective

## *Insights from the EU and Asia Workshops*



- International workshops reinforced the primary goals, and added additional emphasis in complementary areas
  - Potential to work together on common themes and build off each other's work
- EU Workshop, Hamburg, Germany (C. Sotomayor Torres, J. Welser)
  - Increased emphasis on “More-than-Moore” applications of nanoelectronics, particularly in analog devices, to enhance functionality
  - Strong focus on basic science research to discover new phenomena
- Japan-Korea-Taiwan Workshop, Tsukuba, Japan (M.-H. Hong, S. Wolf)
  - Also emphasized “More-than-Moore”, but with more focus on exploring novel state variables and materials (e.g. topological insulators, orbitronics, superconductivity, etc.)
  - Strong interest in quantum computing
- Australia-China-India-Singapore, Singapore (A. Wee, S. Wolf)
  - Strong emphasis on full quantum information systems, for computation and communication
  - Increased interest in molecular electronics, as well as heterogeneous materials integration
- All groups emphasized the need for interdisciplinary teaming, focusing on the application as the driver, and continued strong investment in both research and infrastructure for nanoelectronics work



# NRI Benchmarking New Switch Technologies

## General Observations



Information Token	Transport Mechanism
Spin waves	Drift
Spin (Single / Few)	Diffusion
Magnetic Field (Collective Spin)	Ballistic Transport
PseudoSpin	Spin Conduction
Heat	Electromagnetic Waves
Excitons	Simple Conduction
Plasmons	Band Transport
Charge	EM quasi-particle in surface plasmon-polariton mode

- Maturing of devices over the past year; more understanding of intrinsic responses
- Substantial clustering of data across multiple tokens
- Token transfer (interconnect) becoming even more important
  - Can influence relative device value
- NRI Architecture results make clear the emerging need for parallelism
  - Important for teams to add circuit designers and to consider non-Von Neumann and/or application-specific architectures
  - Positive Sign: Schematics and SPICE now regularly appear in PI reports
- No clear “winner” – but clearer understanding of device capability has emerged
  - Primary advantages: Power, Area; Primary challenges: Speed
- Increased focus on circuit implementations to take advantage of novel device attributes (e.g. non-volatility, complex functions) required
  - Will continue to refine benchmark process to include relevant parameters – not eliminating ideas based solely on our current CMOS-based metrics



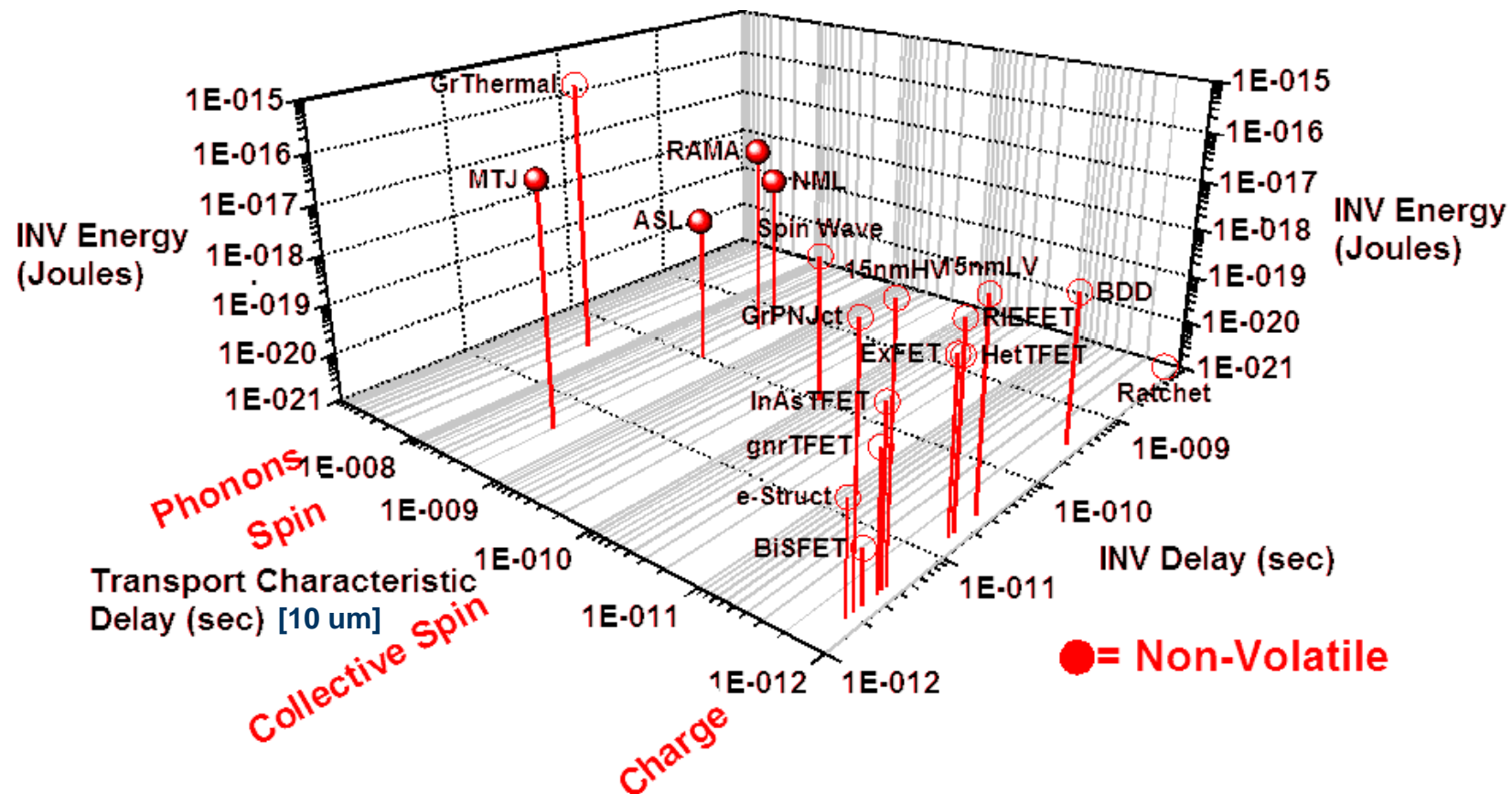
# NRI Benchmarking

## Typical Data



Invited Paper: "Device and Architecture Outlook for Beyond CMOS Switches," K. Bernstein, R.K. Cavin, W. Porod, A. Seabaugh, and J. Welser, *Proceedings of the IEEE Special Issue - Nanoelectronics Research: Beyond CMOS Information Processing*, Vol. 98, No. 12, December 2010.

### Intrinsic Switch / Transport Venue Composite Benchmarking

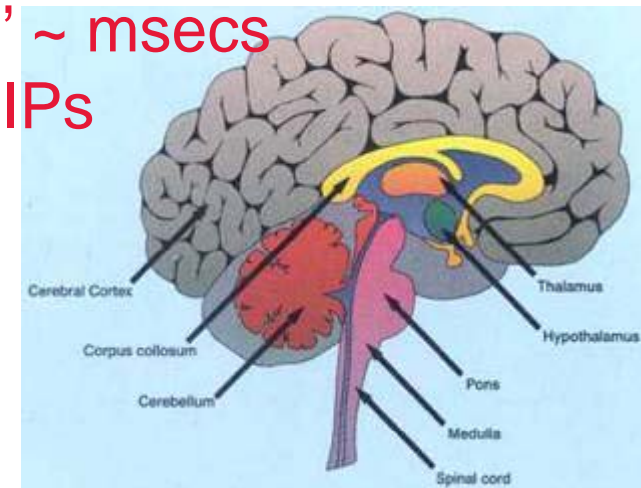




- Many different device ideas being considered – some ‘likely’ attributes compared to CMOS:

- Slower
- Denser / 3D
- Local interconnect focused
- Uniform arrays / sea-of-gates
- Variability still an issue

‘Switch’ ~ msec  
~ $10^8$  MIPs  
~30W



Proof of concept?

- Architecture / System Question:
  - How to get high computation throughput with these attributes?

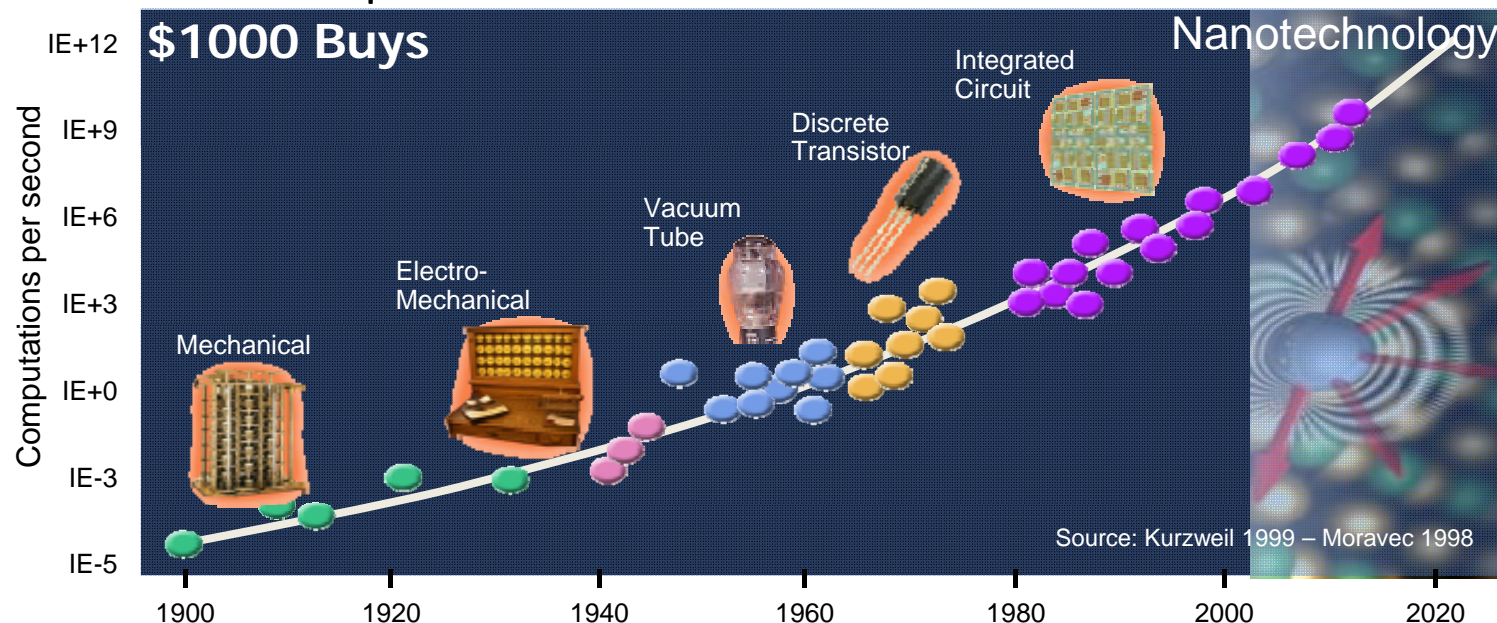


# Nanoelectronics Impact on Society:

## *To Continue the Benefits, Continue the Curve*

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- Nanoelectronics plays a major role in tackling most of society's challenges
  - High Performance Computing: behind every major scientific advance
  - Energy: low energy devices, sensors, "smart" appliances & energy grid
  - Bio / Health: in vivo sensors, health monitoring, drug delivery, drug discovery
- Increased proliferation of mobile devices, sensors, and always-on connectivity will alter how we interact with each other and the planet
  - More remote interactions, workforce globalization, remote delivery of services
  - Continued focus on environmental & societal impact of embedded devices
- Microelectronics was THE economic driver for the last half of the 20<sup>th</sup> century  
Nanoelectronics is poised to drive the first half of the 21<sup>st</sup>



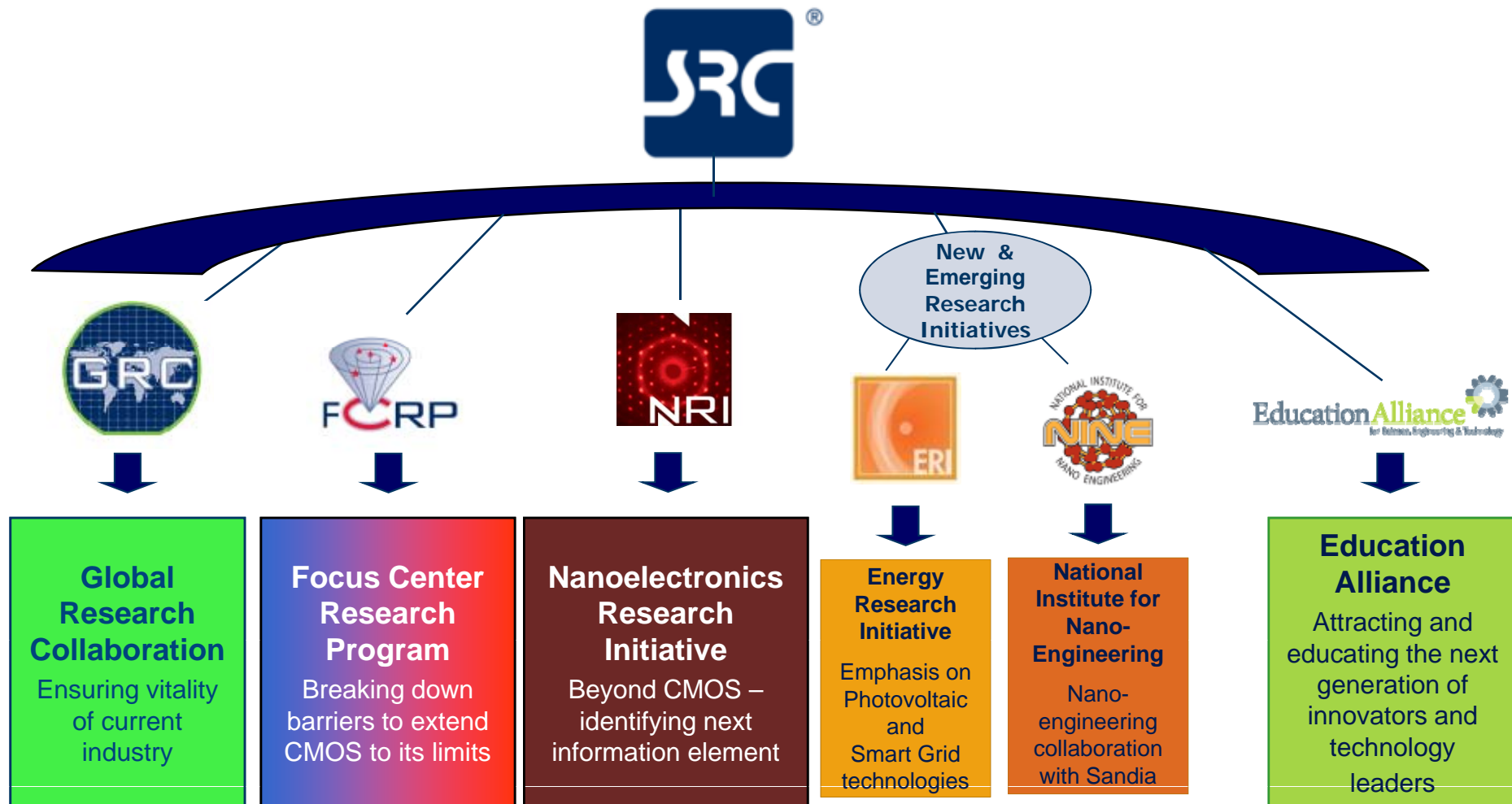


# Backups



# Semiconductor Research Corporation

*A Family of Distinct, Related Program Entities*





# Nanoelectronics Research Initiative Origins



- 2001-2004: Defining Research Needs
  - ITRS-Emerging Research Device Technical Working Group
  - NSF-SRC Ind-Academia-Govt "Silicon Nanoelectronics and Beyond" Workshops
  - SIA Technology Strategy Committee workshops
  - *Defined 13 Research Vectors for finding the "next switch"*
  - *SIA Board passes resolution for formation of NRI*

- Current Member Companies:



GLOBALFOUNDRIES



TEXAS  
INSTRUMENTS



- Sep 2005: First NRI and NRI-NSF Solicitations released
- Jan 2006: Research Programs started



- Sep 2007: NIST joins NRI



- NRI partnership model highlighted in as sidebar in the National Nanotechnology Initiative (NNI) Strategic Plan (NNCO, 1/08)
  - Also called out in the House Appropriation Committee report (FY2008)
  - NRI showcased in Small Times' annual nanotechnology university issue